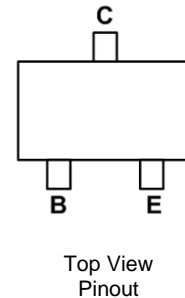
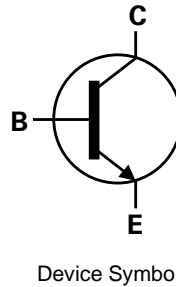


Features

- Epitaxial Planar Die Construction
- Ultra-Small Surface-Mount Package
- Complementary PNP Type: [MMST5401](#)
- Ideal for Low Power Amplification and Switching
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at <https://www.diodes.com/products/automotive/automotive-products/>.**
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability. <https://www.diodes.com/quality/product-definitions/>

Mechanical Data

- Package: SOT323
- Package Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 [Ⓔ]
- Weight: 0.006 grams (Approximate)

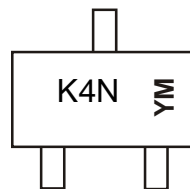


Ordering Information (Note 4)

| Orderable Part Number | Package | Marking | Reel Size (inches) | Tape Width (mm) | Packing | |
|-----------------------|---------|---------|--------------------|-----------------|---------|---------|
| | | | | | Qty. | Carrier |
| MMST5551-7-F | SOT323 | K4N | 7 | 8 | 3,000 | Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



K4N = Product Type Marking Code
 YM = Date Code Marking
 Y or Y = Year (ex: M = 2025)
 M or M = Month (ex: 9 = September)

Date Code Key

| Year | 2003 | - | 2025 | 2026 | 2027 | 2028 | 2029 | 2030 | 2031 | 2032 | 2033 | 2034 |
|------|------|---|------|------|------|------|------|------|------|------|------|------|
| Code | P | - | M | N | P | R | S | T | U | V | W | X |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|------------------------------|------------------|-------|------|
| Collector-Base Voltage | V _{CBO} | 180 | V |
| Collector-Emitter Voltage | V _{CEO} | 160 | V |
| Emitter-Base Voltage | V _{EBO} | 6.0 | V |
| Continuous Collector Current | I _C | 200 | mA |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|--|-----------------------------------|-------------|------|
| Power Dissipation (Note 5) | P _D | 200 | mW |
| Thermal Resistance, Junction to Ambient (Note 5) | R _{θJA} | 625 | °C/W |
| Thermal Resistance, Junction to Case (Note 5) | R _{θJC} | 159 | °C/W |
| Thermal Resistance, Junction to Lead (Note 6) | R _{θJL} | 291 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

ESD Ratings (Note 7)

| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--|---------|-------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | 4,000 | V | 3A |
| Electrostatic Discharge - Machine Model | ESD MM | 400 | V | C |
| Electrostatic Discharge - Charged Device Model | ESD CDM | 1,000 | V | C3 |

- Notes:
5. For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 6. Thermal resistance from junction to solder-point at the end of the collector lead.
 7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Max | Unit | Test Condition |
|--------------------------------------|----------------------|----------------|---------------|----------|--|
| OFF CHARACTERISTICS (Note 8) | | | | | |
| Collector-Base Breakdown Voltage | V _{CB0} | 180 | — | V | I _C = 100μA, I _E = 0 |
| Collector-Emitter Breakdown Voltage | V _{CEO} | 160 | — | V | I _C = 1.0mA, I _B = 0 |
| Emitter-Base Breakdown Voltage | V _{EBO} | 6 | — | V | I _E = 10μA, I _C = 0 |
| Collector Cutoff Current | I _{CBO} | — | 50 | nA μA | V _{CB} = 120V, I _E = 0 V _{CB} = 120V, I _E = 0, T _A = +100°C |
| Emitter Cutoff Current | I _{EBO} | — | 50 | nA | V _{EB} = 4.0V, I _C = 0 |
| ON CHARACTERISTICS (Note 8) | | | | | |
| DC Current Gain | h _{FE} | 80 80 30 | — 250 — | — | I _C = 1.0mA, V _{CE} = 5.0V I _C = 10mA, V _{CE} = 5.0V I _C = 50mA, V _{CE} = 5.0V |
| Collector-Emitter Saturation Voltage | V _{CE(sat)} | — | 0.15 0.20 | V | I _C = 10mA, I _B = 1.0mA I _C = 50mA, I _B = 5.0mA |
| Base-Emitter Saturation Voltage | V _{BE(sat)} | — | 1.0 | V | I _C = 10mA, I _B = 1.0mA I _C = 50mA, I _B = 5.0mA |
| SMALL-SIGNAL CHARACTERISTICS | | | | | |
| Output Capacitance | C _{obo} | — | 6.0 | pF | V _{CB} = 10V, f = 1.0MHz, I _E = 0 |
| Small-Signal Current Gain | h _{fe} | 50 | 250 | — | V _{CE} = 10V, I _C = 1.0mA, f = 1.0kHz |
| Current Gain-Bandwidth Product | f _T | 100 | 300 | MHz | V _{CE} = 10V, I _C = 10mA, f = 100MHz |
| Noise Figure | NF | — | 8.0 | dB | V _{CE} = 5.0V, I _C = 200μA, R _S = 1.0Ω, f = 1.0kHz |

Note: 8. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

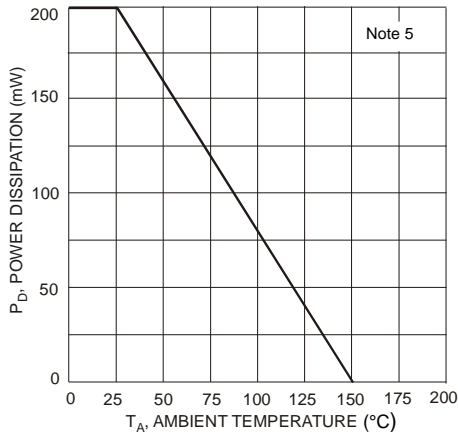


Fig. 1, Max Power Dissipation vs. Ambient Temperature

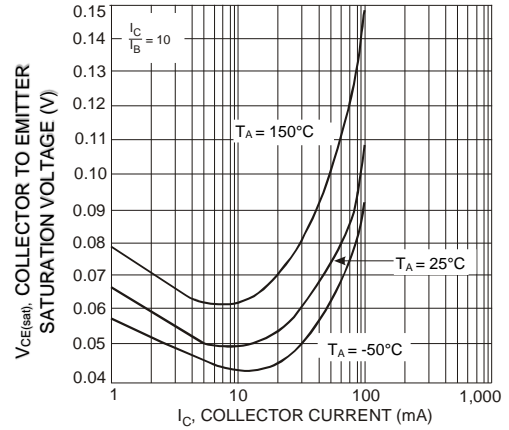


Fig. 2, Collector Emitter Saturation Voltage vs. Collector Current

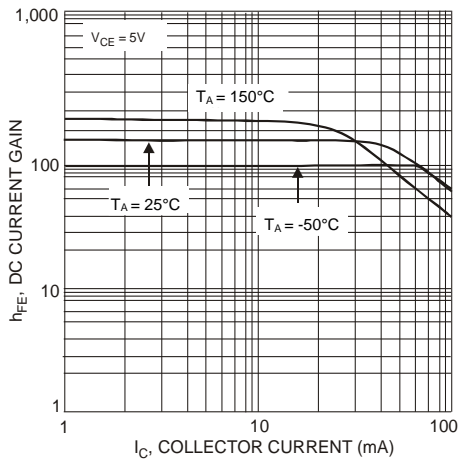


Fig. 3, DC Current Gain vs. Collector Current

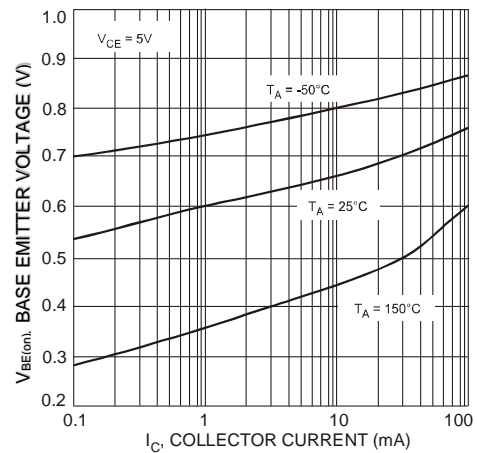


Fig. 4, Base Emitter Voltage vs. Collector Current

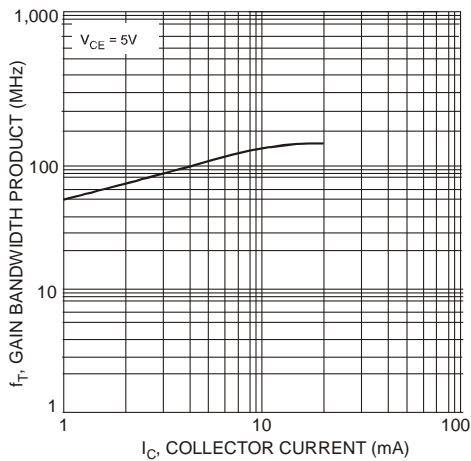
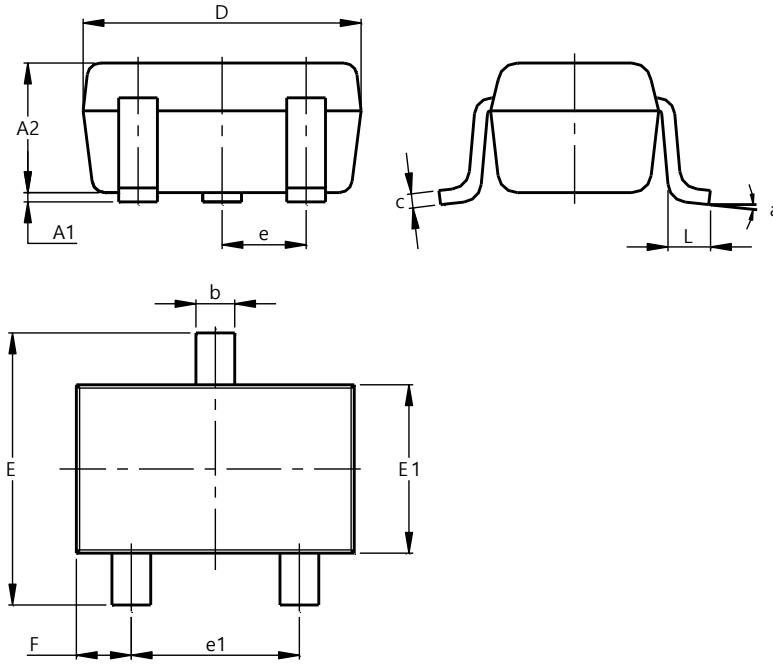


Fig. 5, Gain Bandwidth Product vs. Collector Current

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT323

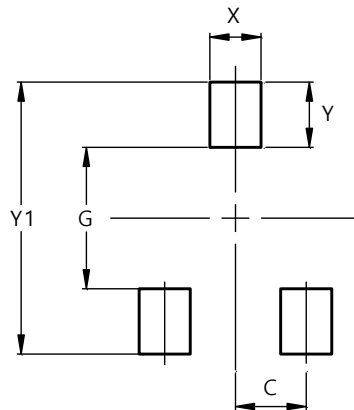


| SOT323 | | | |
|----------------------|-----------|-------|-------|
| Dim | Min | Max | Typ |
| A1 | 0.00 | 0.10 | 0.05 |
| A2 | 0.90 | 1.00 | 0.95 |
| b | 0.25 | 0.40 | 0.30 |
| c | 0.10 | 0.18 | 0.11 |
| D | 1.80 | 2.20 | 2.15 |
| E | 2.00 | 2.20 | 2.10 |
| E1 | 1.15 | 1.35 | 1.30 |
| e | 0.650 BSC | | |
| e1 | 1.20 | 1.40 | 1.30 |
| F | 0.375 | 0.475 | 0.425 |
| L | 0.25 | 0.40 | 0.30 |
| a | 0° | 8° | -- |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT323



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 0.650 |
| G | 1.300 |
| X | 0.470 |
| Y | 0.600 |
| Y1 | 2.500 |

Note: For high-voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.

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